

# Characterisation of prototype SiGe monolithic pixel detectors for the TT-PET project

Dean Forshaw  
On behalf of the TT-PET Collaboration

University of Bern  
Albert Einstein Center for Fundamental Physics



**UNIVERSITÉ  
DE GENÈVE**  
FACULTÉ DES SCIENCES  
Section de physique



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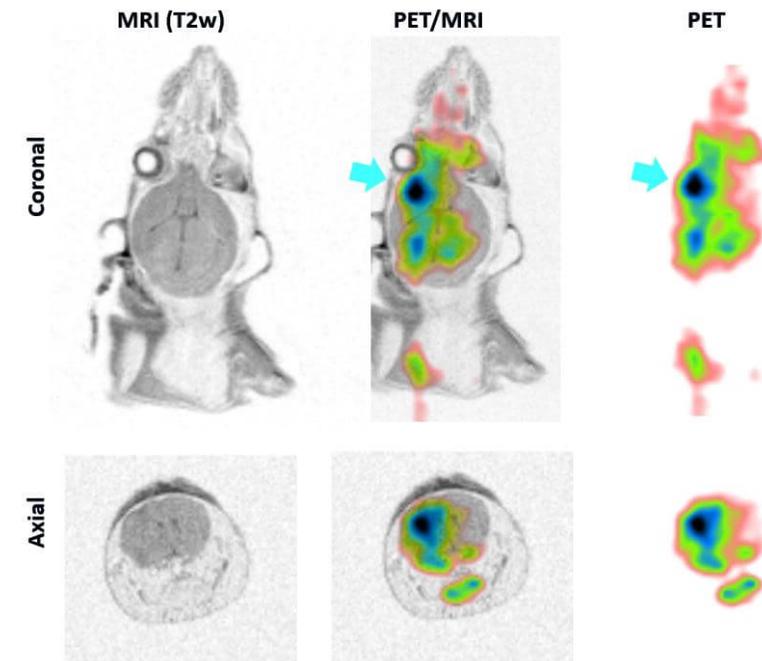
- TT-PET Project
- Scanner Overview
- Monolithic Chip
- Test beam characterization
- TOF simulation
- Prototype-0

# The TT-PET Project

➤ 3-year project to produce a PET Scanner for small animals based on silicon detector technology, insertable in an MRI machine and with 30ps RMS time resolution. The project started in March 2016.

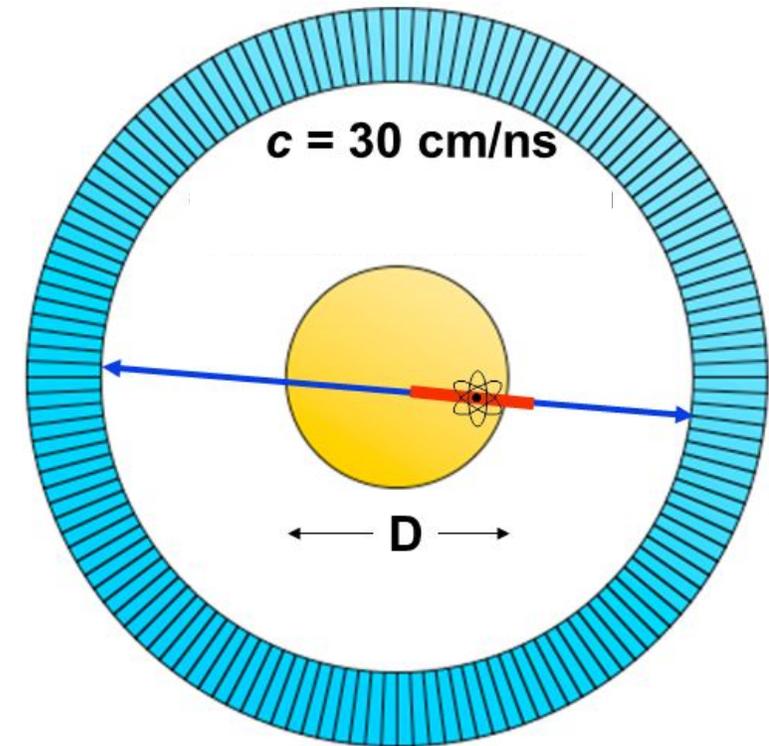
- Collaborating institutes:
  - University of Geneva
  - University of Bern
  - Hôpital cantonale de Genève
- INFN of Roma Tor Vergata
- CERN

TSPO PET/MRI (Inflammation model in mouse brain)



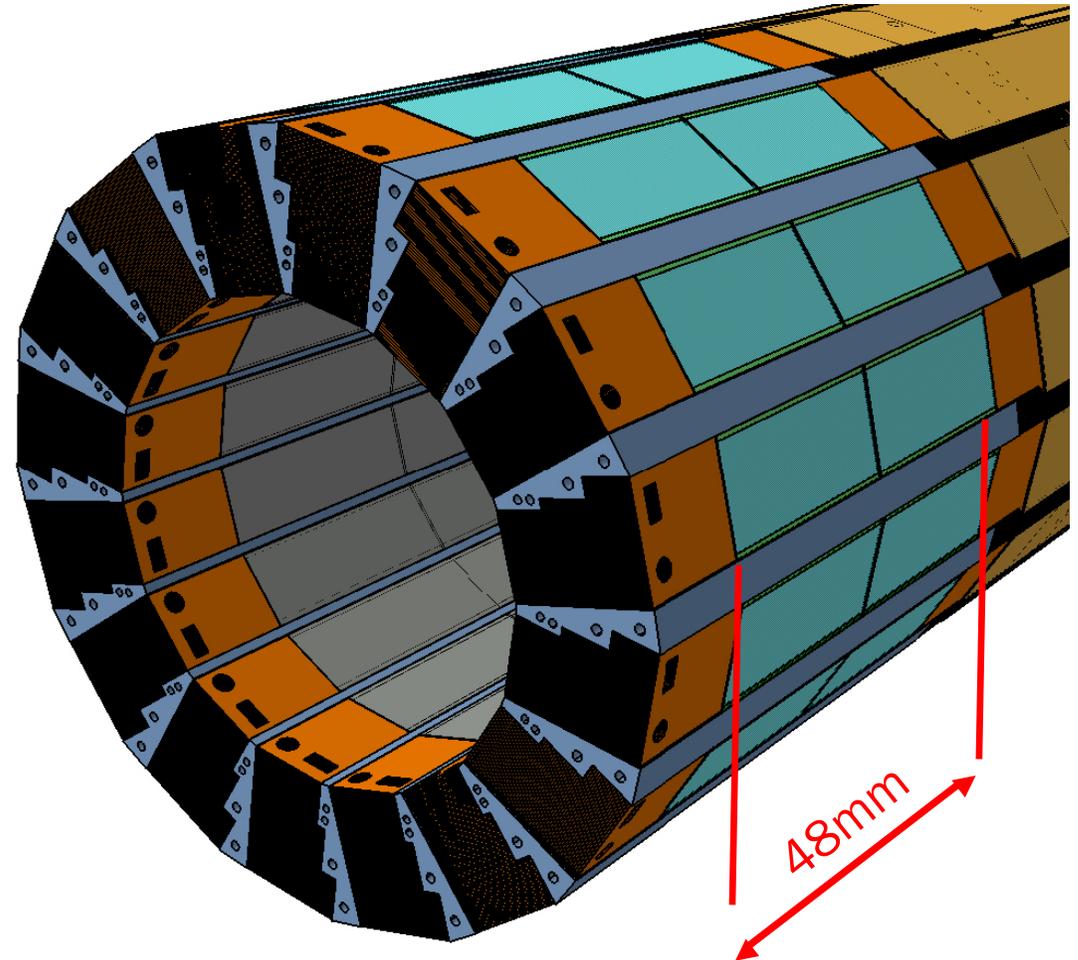
# Why use Time-of-Flight?

- Adding Time-of-Flight information to a PET scan can dramatically increase its performance!
- It is used to localize the source along the line of flight
- It leads to much lower noise, which can be used to increase image quality or decrease radiation dose to the patient



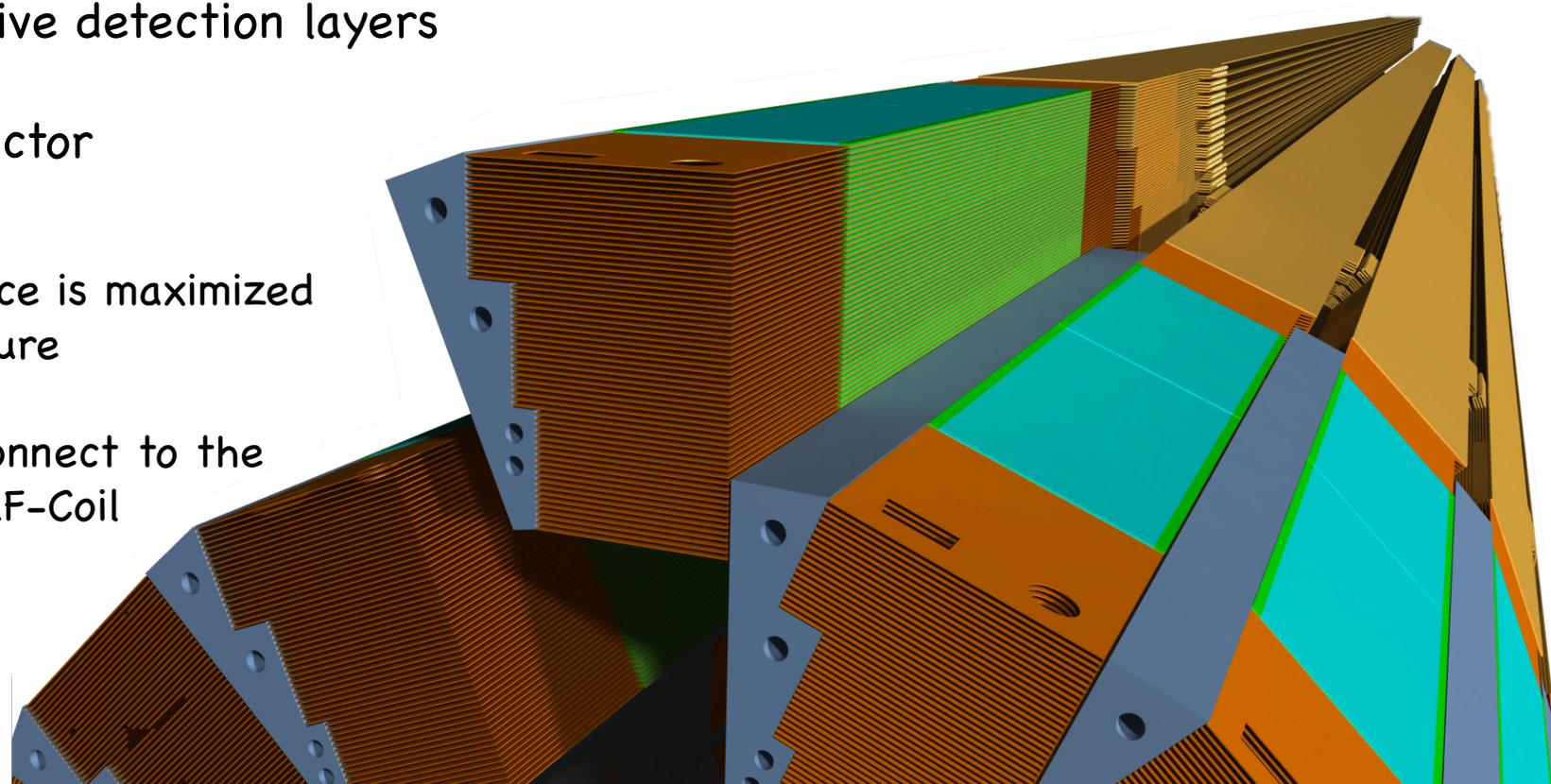
# Scanner Overview

- Designed to fit inside removable RF-Coil for nanoScan 3T
- 16 sensitive towers
- 16 cooling blocks: ceramic/ 3d printed
- Exterior carbon fiber support and cooling pipes not shown
- Inner radius: 65mm
- Outer radius: 80mm
- Total Pixel channels: 1,413,120
- Pixel size:  $500 \times 500 \mu\text{m}^2$

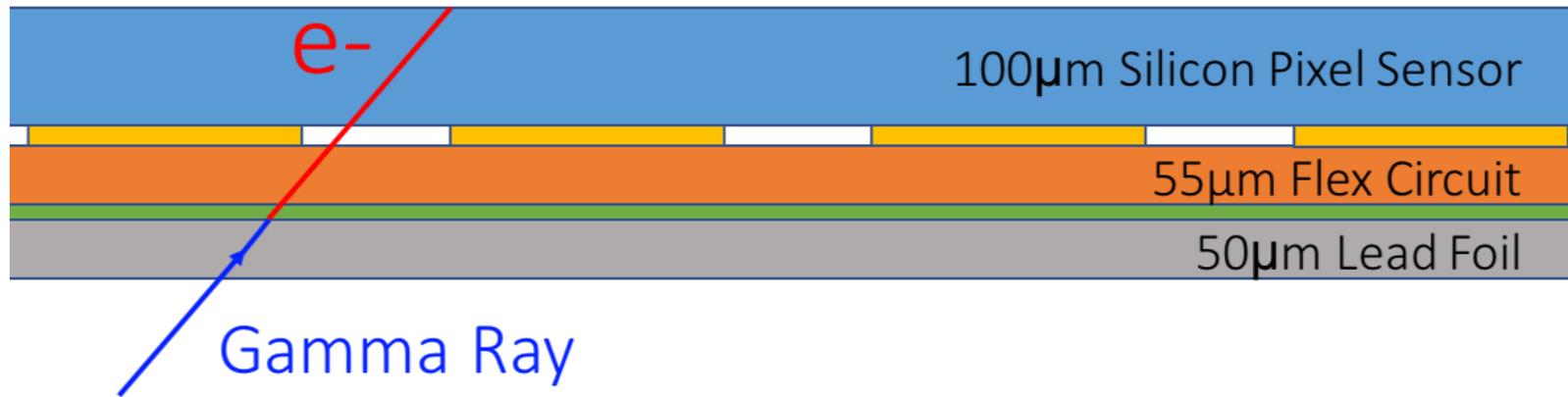


# Scanner Overview

- Sensitive towers composed of many layers of lead, flex circuit, and monolithic pixels sensors
- 1 tower = 60 sensitive detection layers
- Sampling style detector
- Geometrical acceptance is maximized using step like structure
- Longer data cables connect to the DAQ outside of the RF-Coil

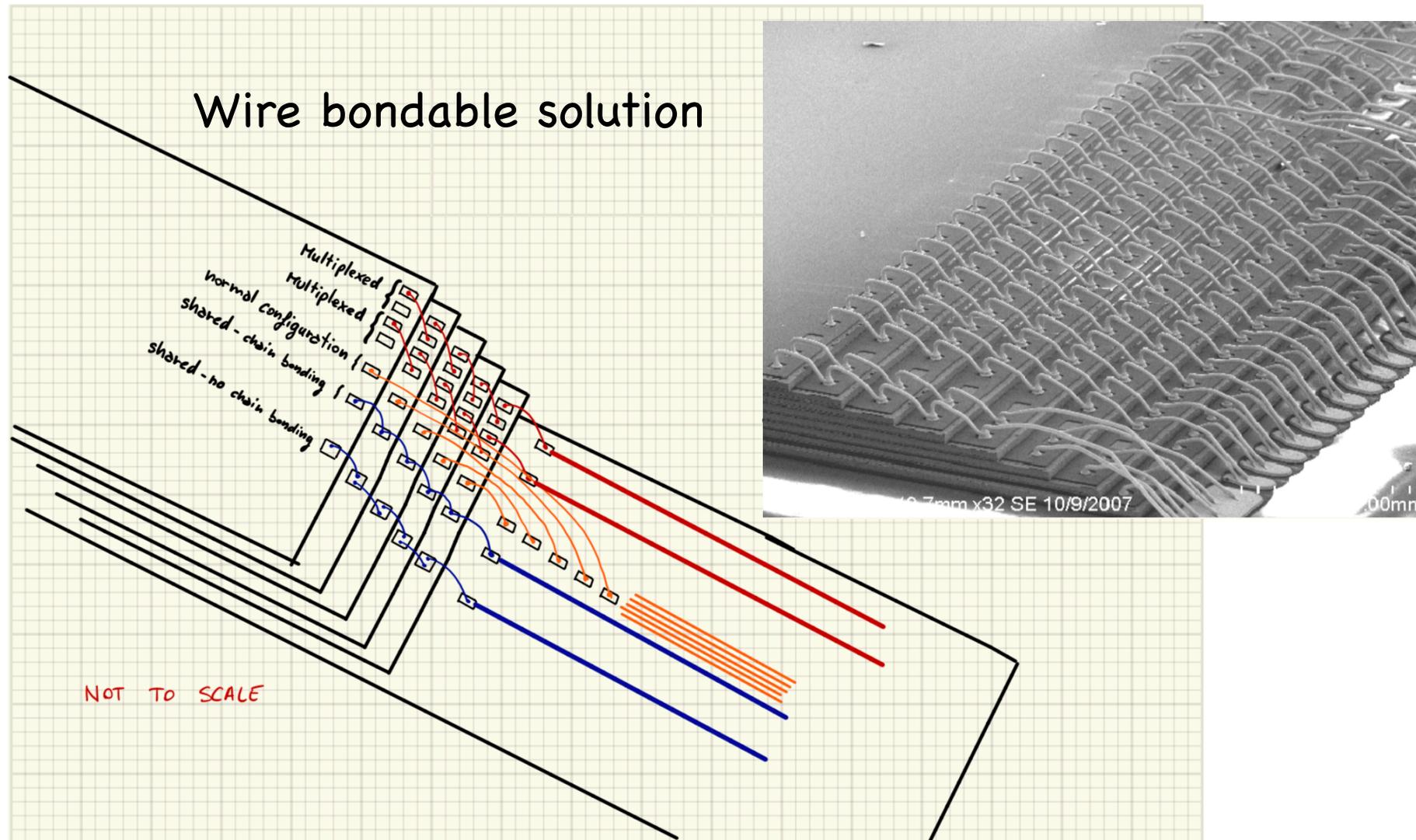


# Single detection layer



- 500x500μm pixels
- Baseline option: bump bond monolithic chip to flex circuit
- Second option: stack multiple chips on top of each other and wire bond together (same process as inside memory chips)

# Single detection layer

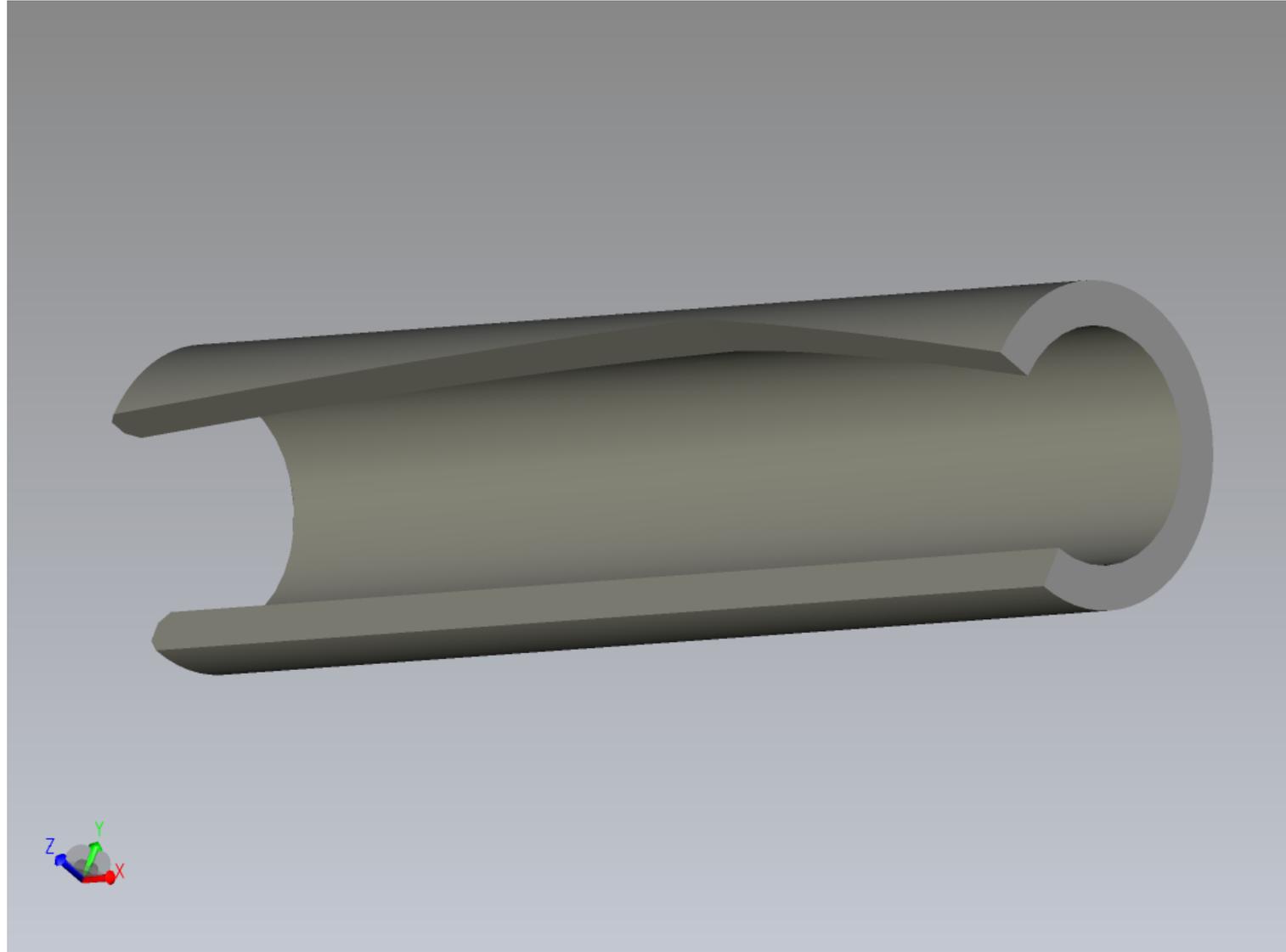


# Mechanics

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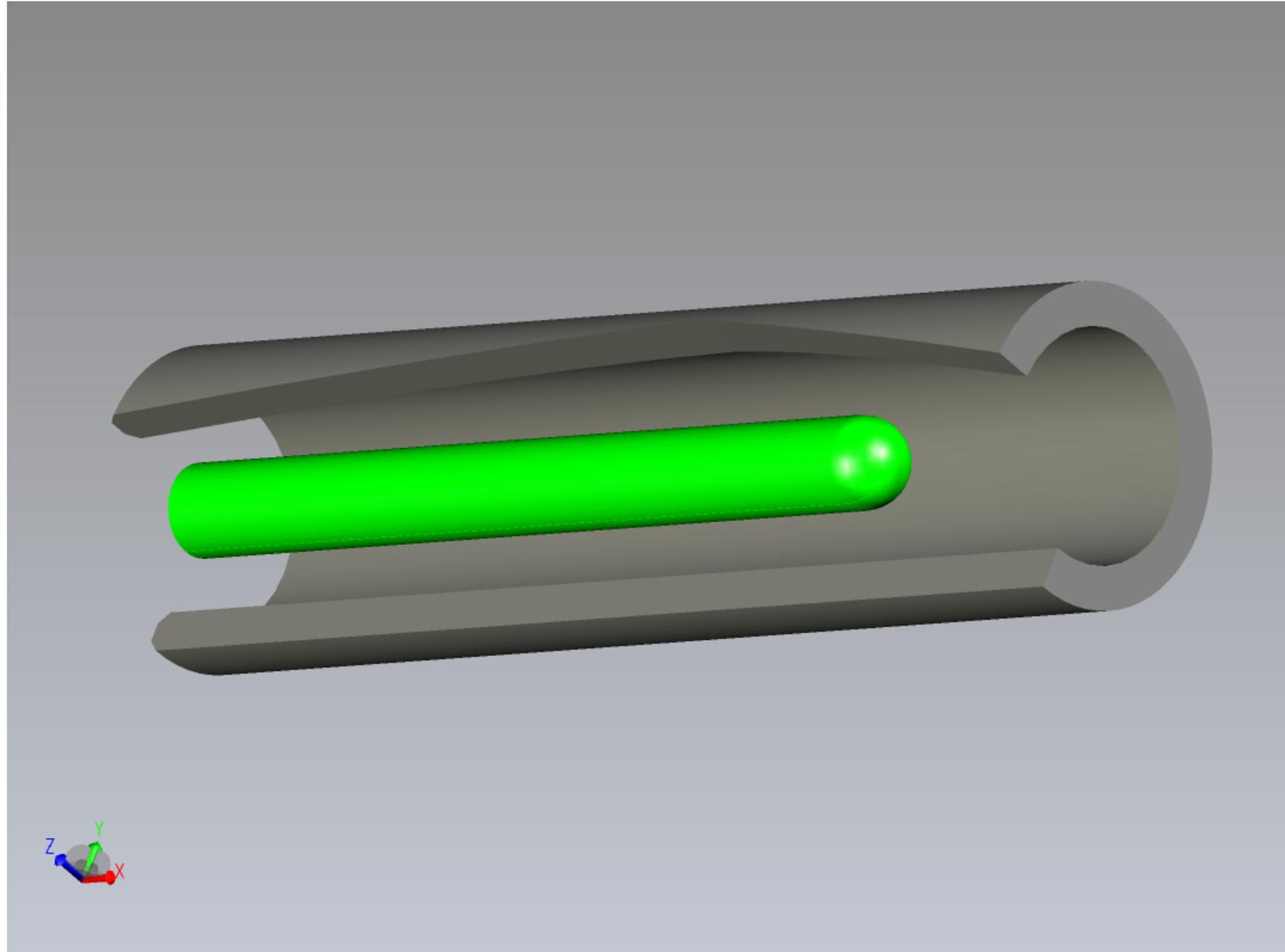


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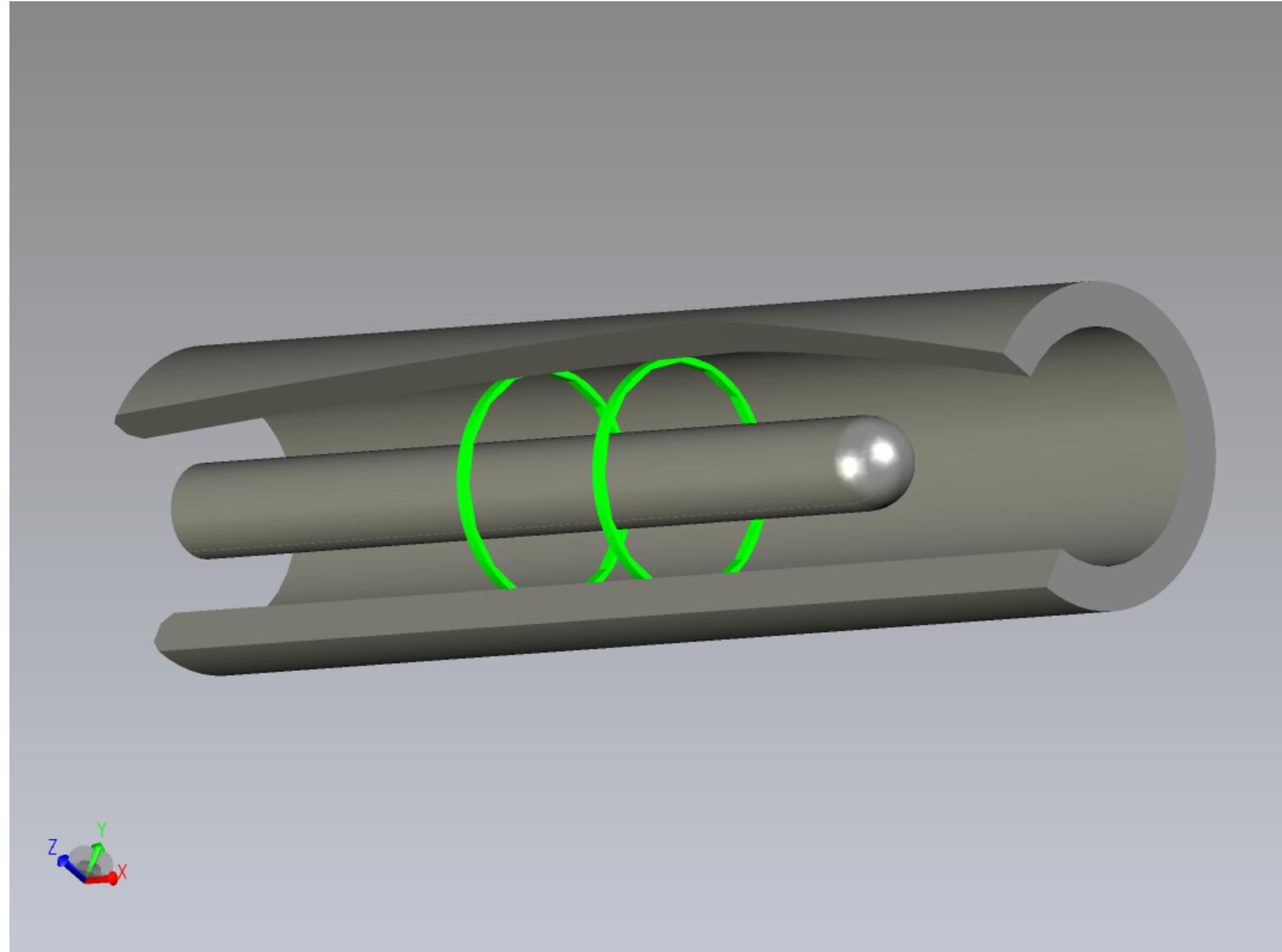


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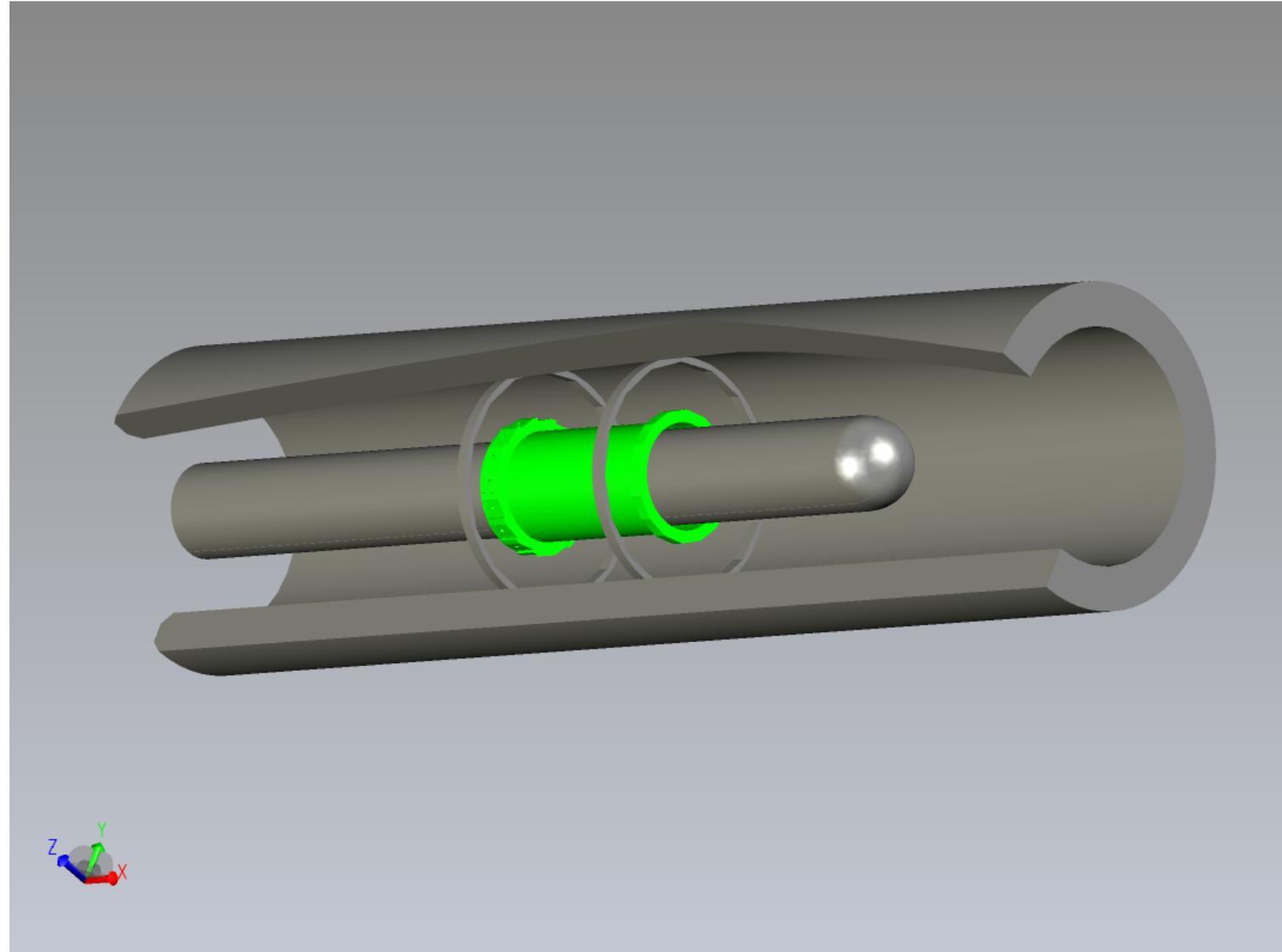


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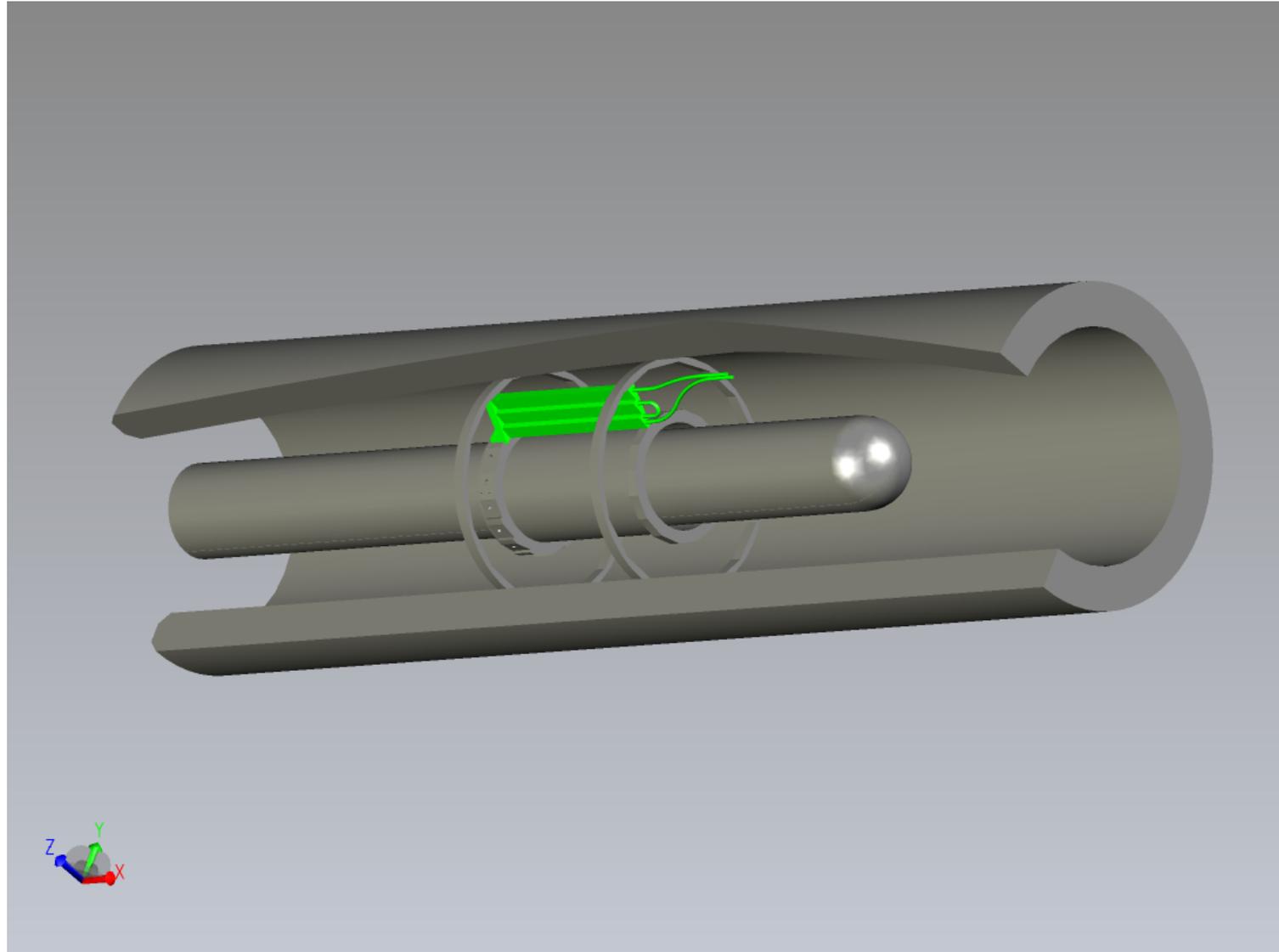


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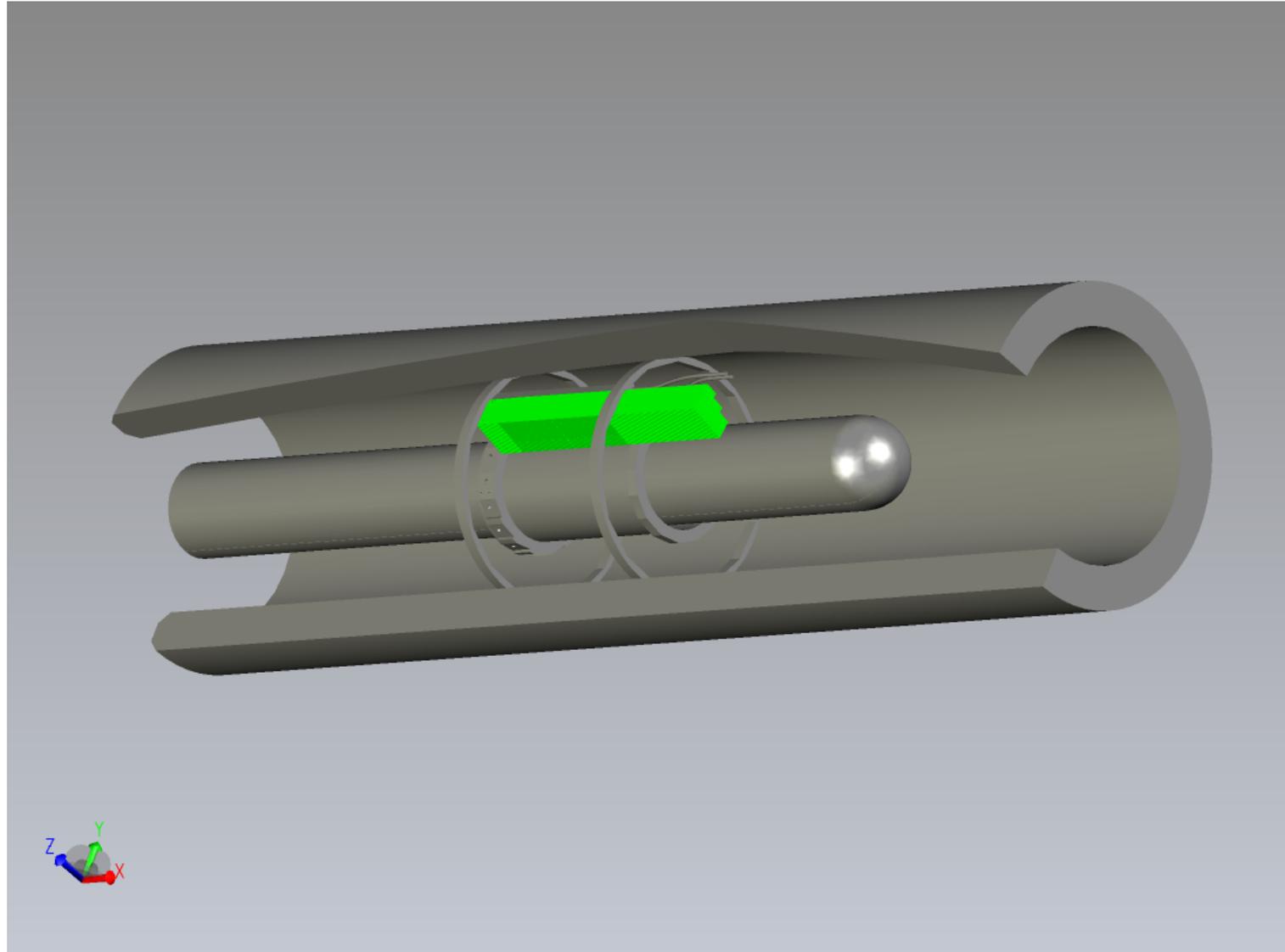


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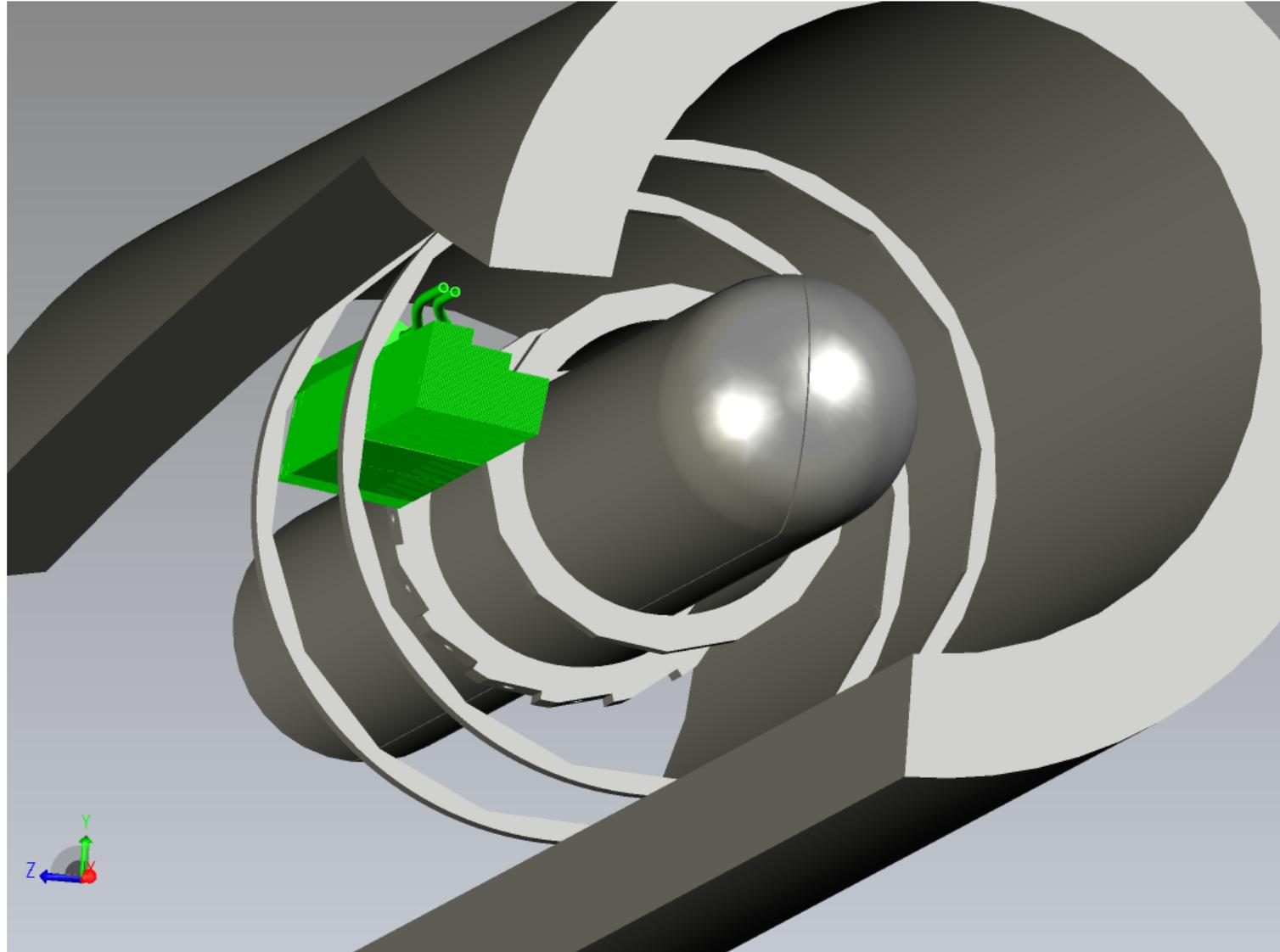


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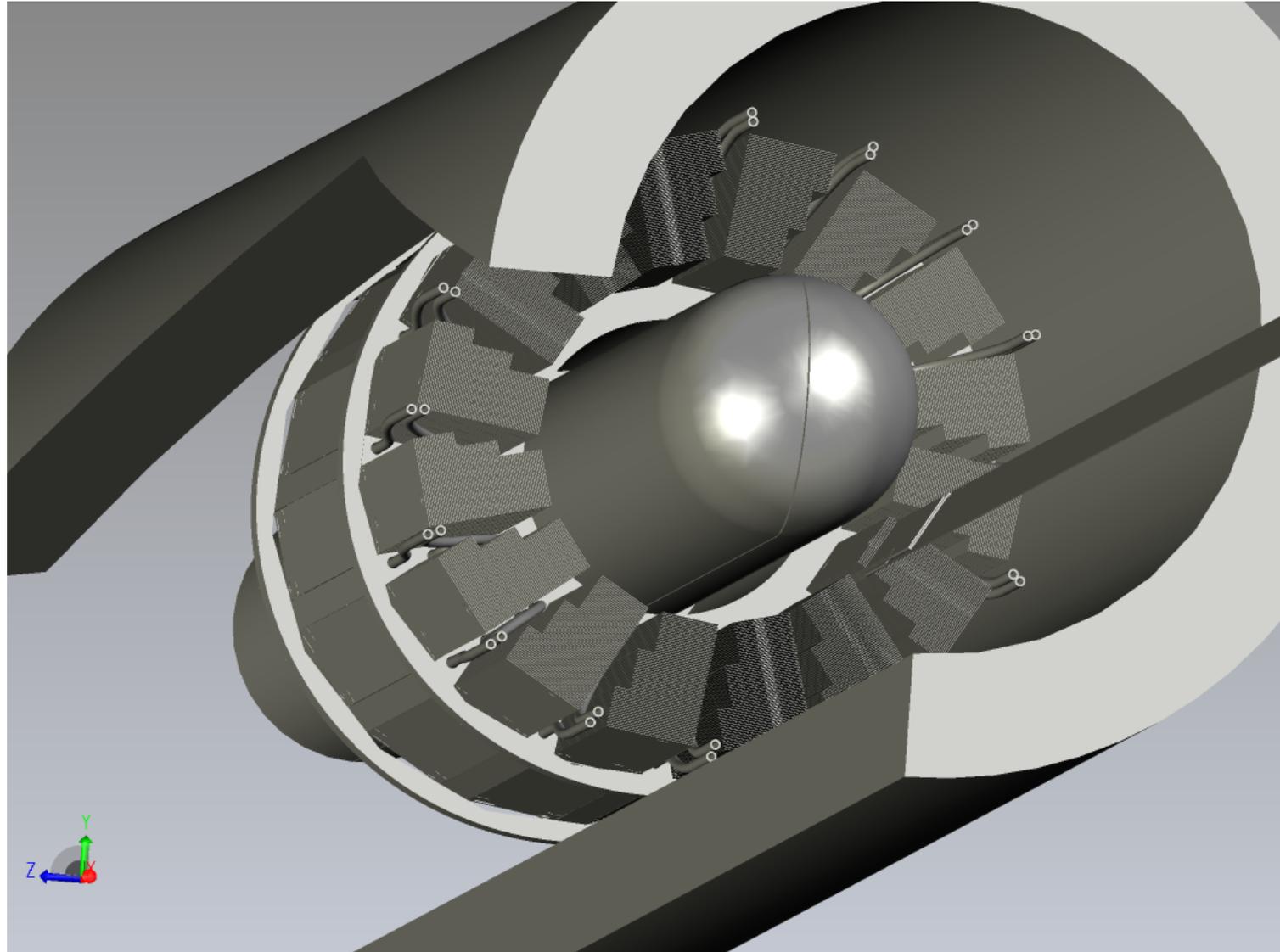


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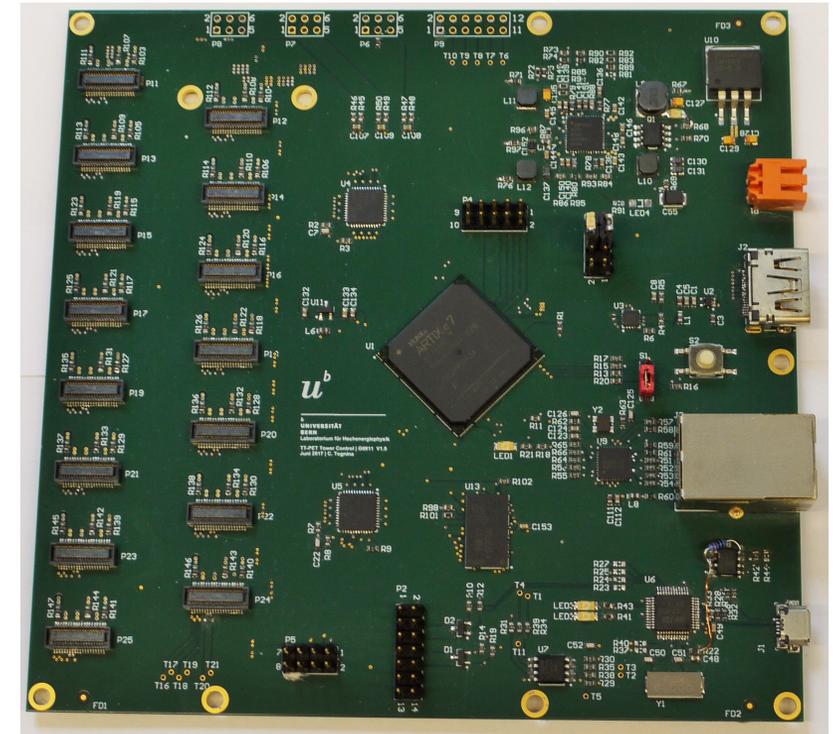
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# Event Rate and Data Pressure

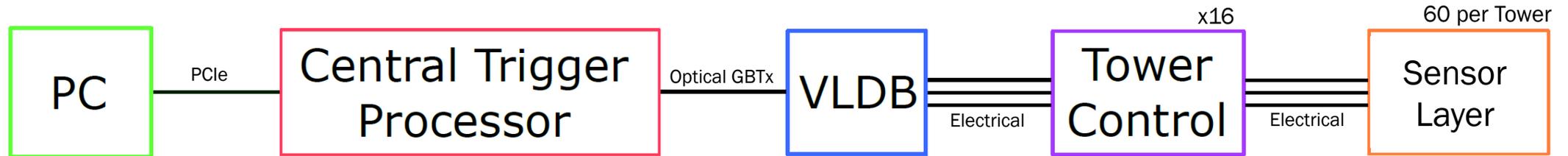
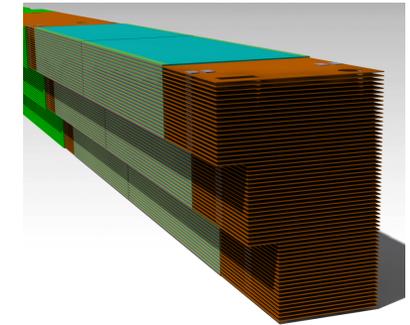
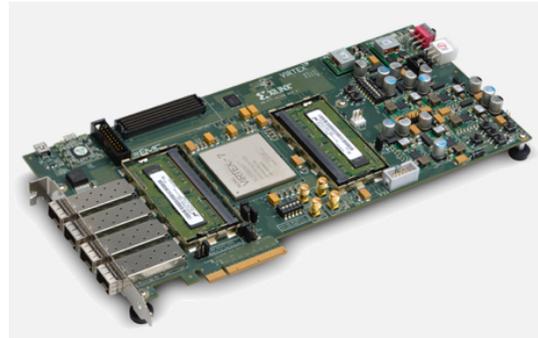
- Readout designed for 50MBq source
  - 19.2 MHz single hit rate
  - 5 MHz possible coincidences
  - 1.2 MHz real coincidences
- System designed for scalability
  - Custom Designed Tower Control board to control one Tower
  - Commercial components used where possible
  - CERN VLDB board (GBTx) used to multiplex multiple tower control DAQ boards



# DAQ chain



Xilinx ZC709



- Control full DAQ chain
- Coincidence check
- Calibration control

- Multiplexer
- Optical to electrical
- Clk fanout

- Custom FPGA board
- Temporary data storage
- Easily scalable

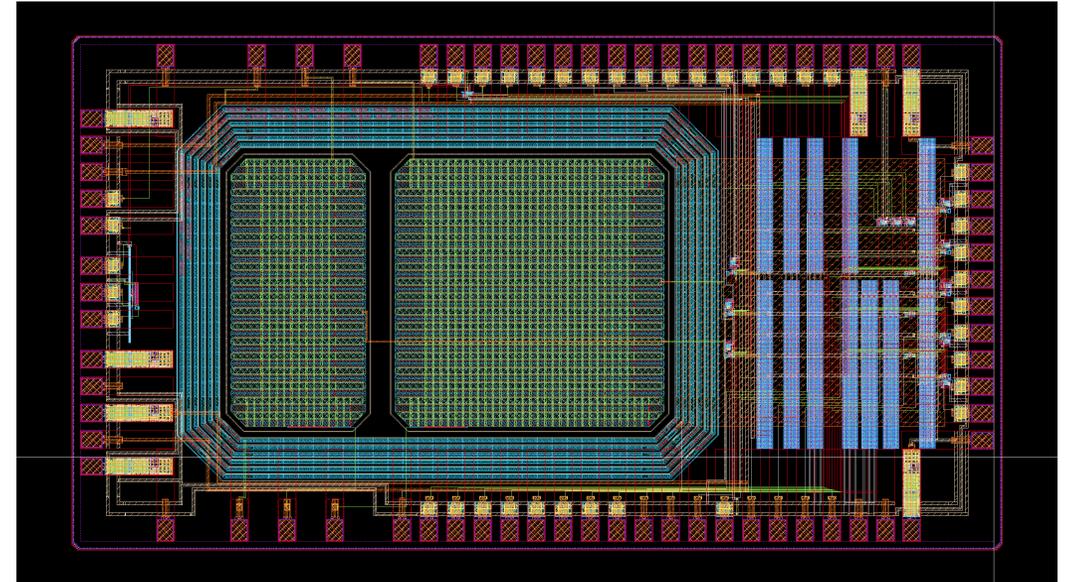
# Pro's and Con's

- Very high granularity, with access to DOI and TOF information for every hit
- Faster signals mean ability to have high-precision timing measurements
- The scanner can be designed to be compatible with an MRI scanner, providing combined MRI-PET images
  
- On the other hand...
- The mechanics of the scanner are really complex (especially the data flex)
- There are a very large number of channels, so the data acquisition scheme is critical
- Every channel must be calibrated → very long procedure

- TT-PET Collaboration
- Scanner Overview
- **Monolithic Chip**
- Test beam characterization
- TOF simulation
- Prototype-0

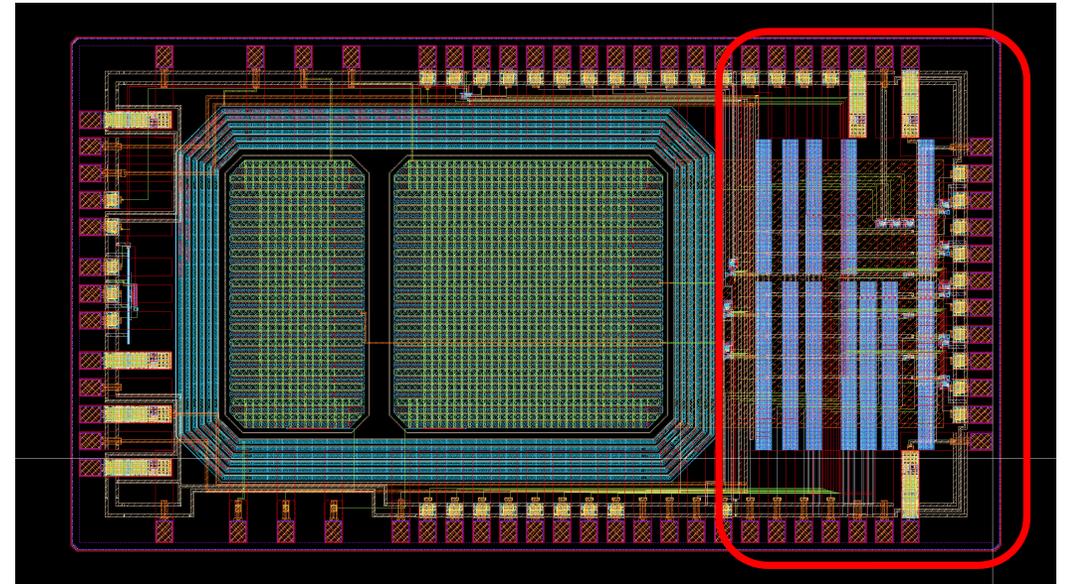
# Monolithic Test chip

- First Monolithic Test ASIC
- SG13S SiGe BiCMOS process from IHP microelectronics (130nm)
- Very High CMOS resistivity suitability (1kΩcm)
- Test custom guard ring design and qualify HV tolerance (180V)
- 1 small pixel 900x450μm<sup>2</sup>
- 1 large pixel 900x900μm<sup>2</sup>
- Geometry type: n-in-p
- ToF RMS (mips): 100ps



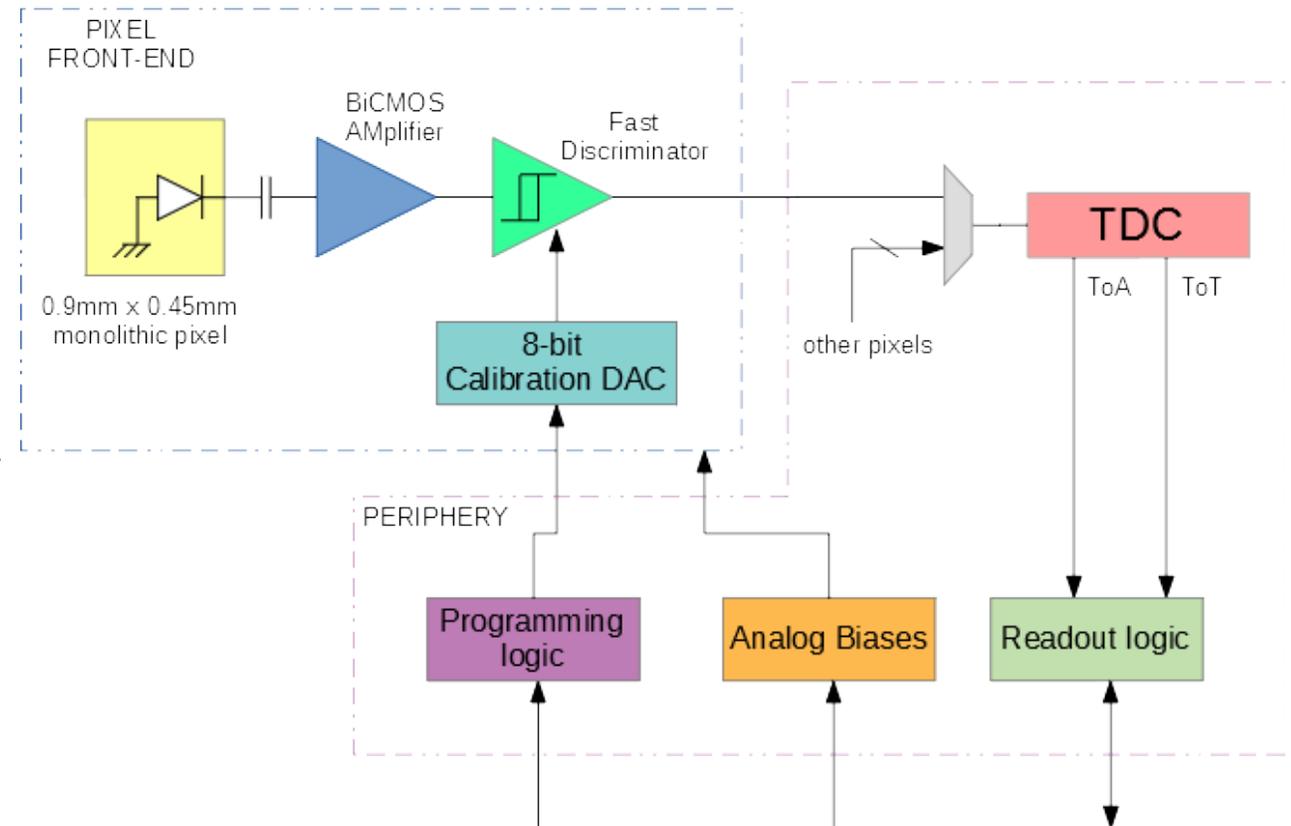
# Monolithic Test chip

- Electronics placed outside of the pixel guard



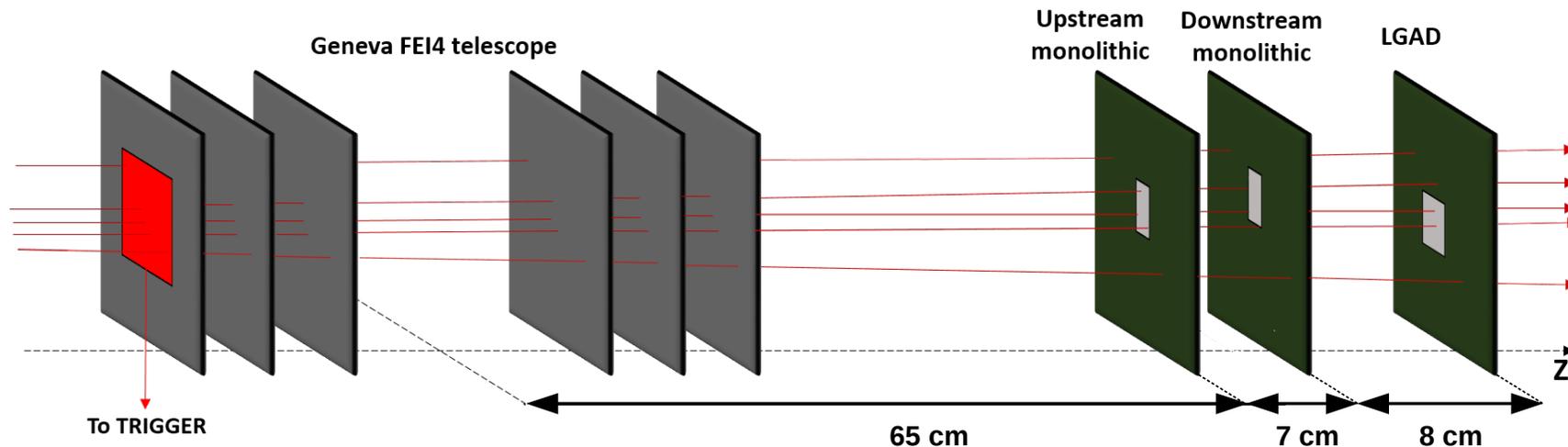
# Monolithic Test chip

- Electronics placed outside of the pixel guard
- SiGe pre-amplifier
- Amplifier rise time 1-2ns
- Discriminator
- Time-over-Threshold measurement



- TT-PET Collaboration
- Scanner Overview
- Monolithic Chip
- **Test beam characterization**
- TOF simulation
- Other prototypes

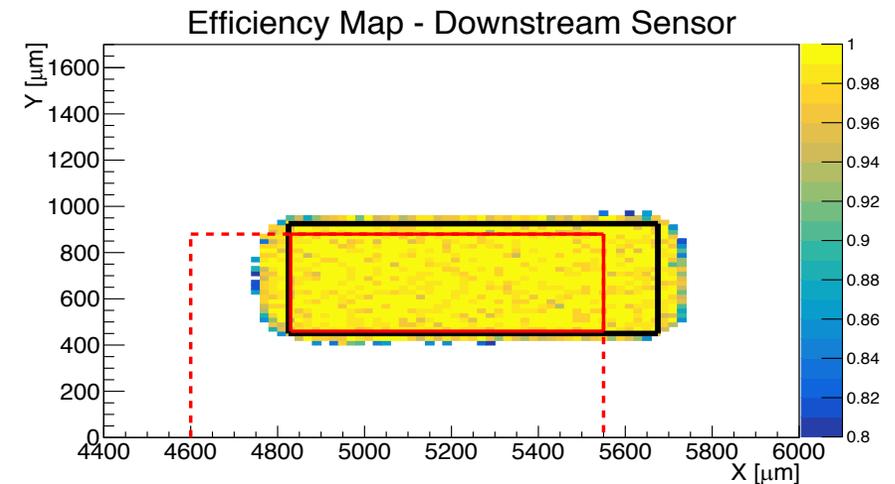
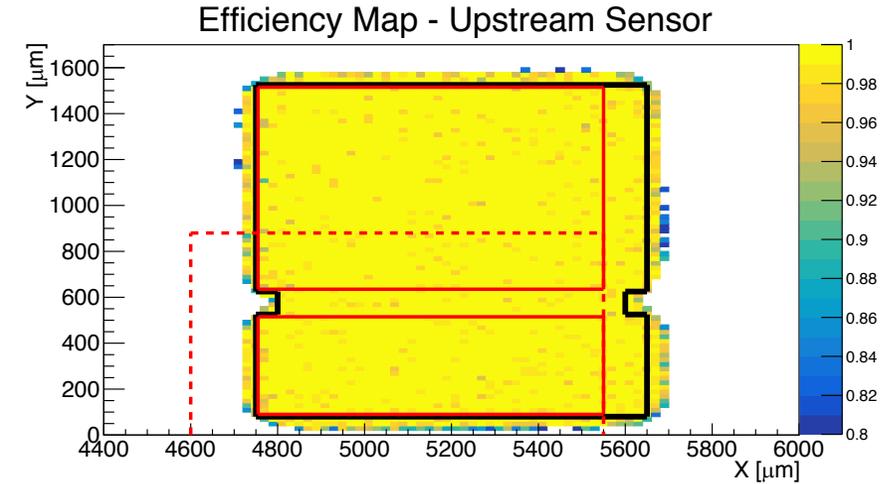
# Test beam setup



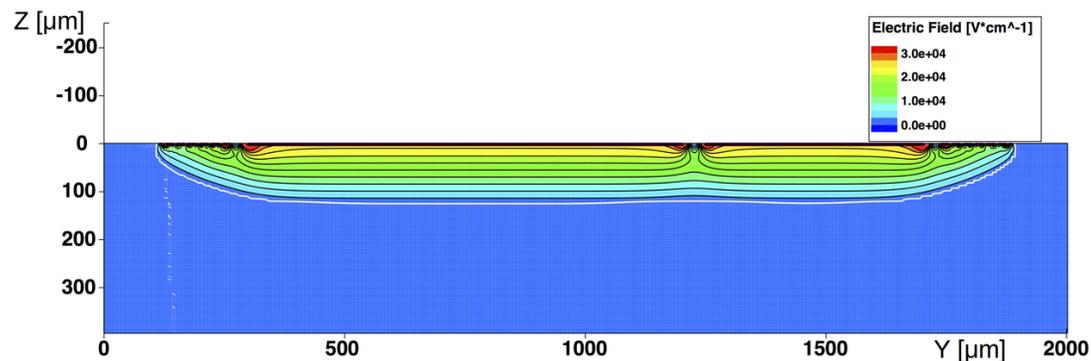
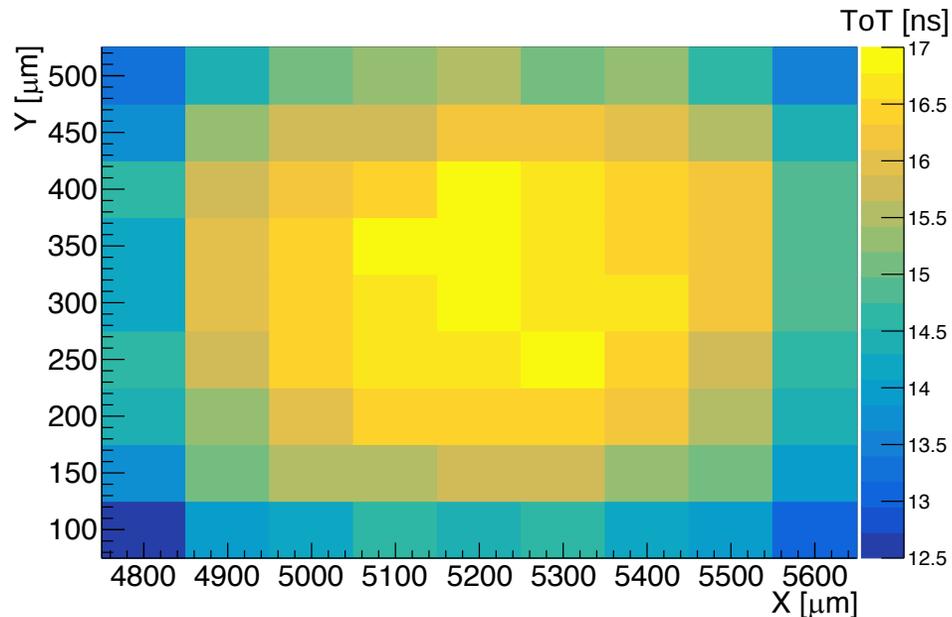
- 180 GeV/c pion beam used (CERN SPS beamline)
- Particle telescope (Geneva FE-I4 telescope) used for tracking
- 2 Monolithic test chips operated at 180V (backside not metalized, and referenced to Gnd)
- LGAD sensor used as final plane (timing reference)

# Efficiency result

- Overlap region (red dashed box)
- Only particle tracks that intersect this ROI are used
- Upstream Sensor efficiency ( $99.79 \pm 0.01\%$ )
- Downstream efficiency ( $99.09 \pm 0.04\%$ )
- No areas of large inefficiency



# Charge Uniformity



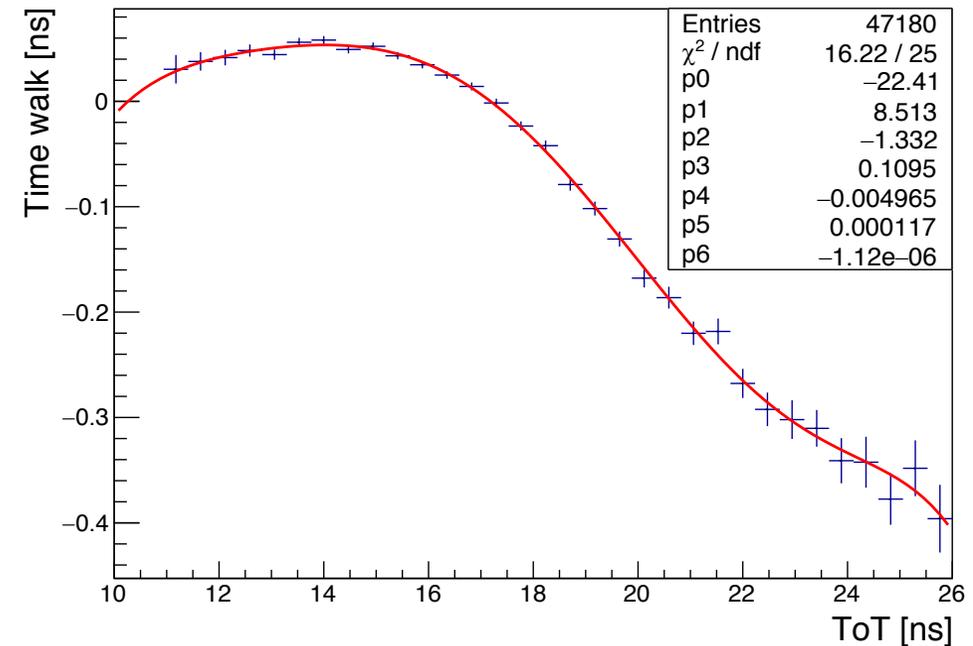
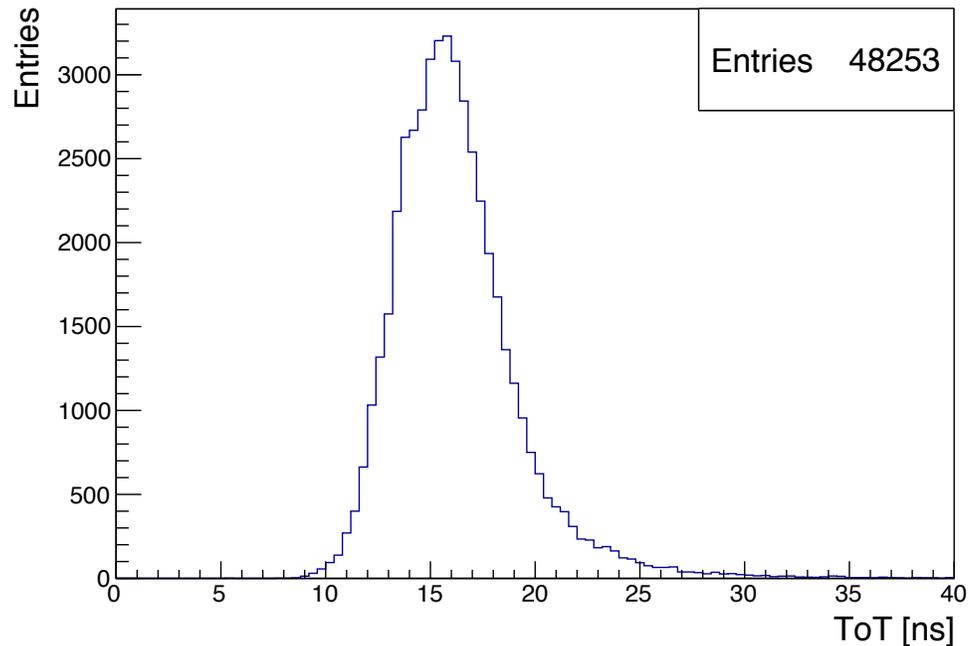
- Amount of charge shown in ToT
- Drop in amount of charge collected around edges of pixel
- Non-uniform electric field near edges
- Sensor not thinned down to 100μm and not backside metalised
- Aim for 2-3 V/μm to maximise  $e^-$  carrier mobility

# ToT and time-walk correction

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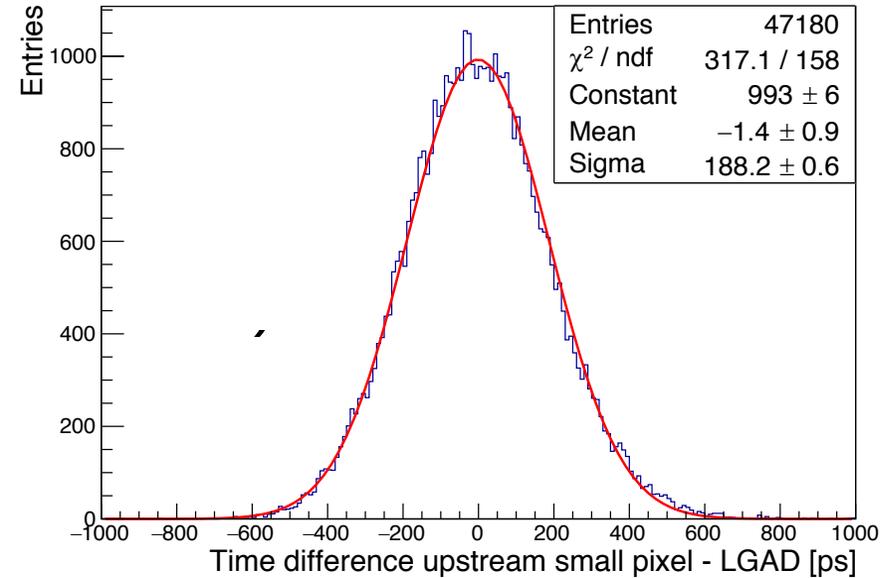
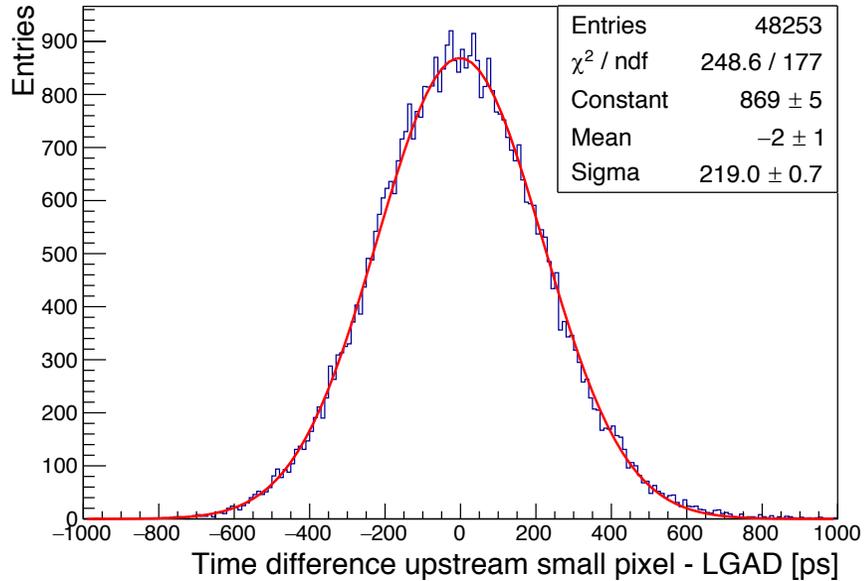
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- Tot distribution on left
- Time-walk correction done using a polynomial fit
- Spread of the time-walk and SNR information used to estimate actual pre-amp peaking time <2ns (agree with our cadence simulations)

# ToF measurement



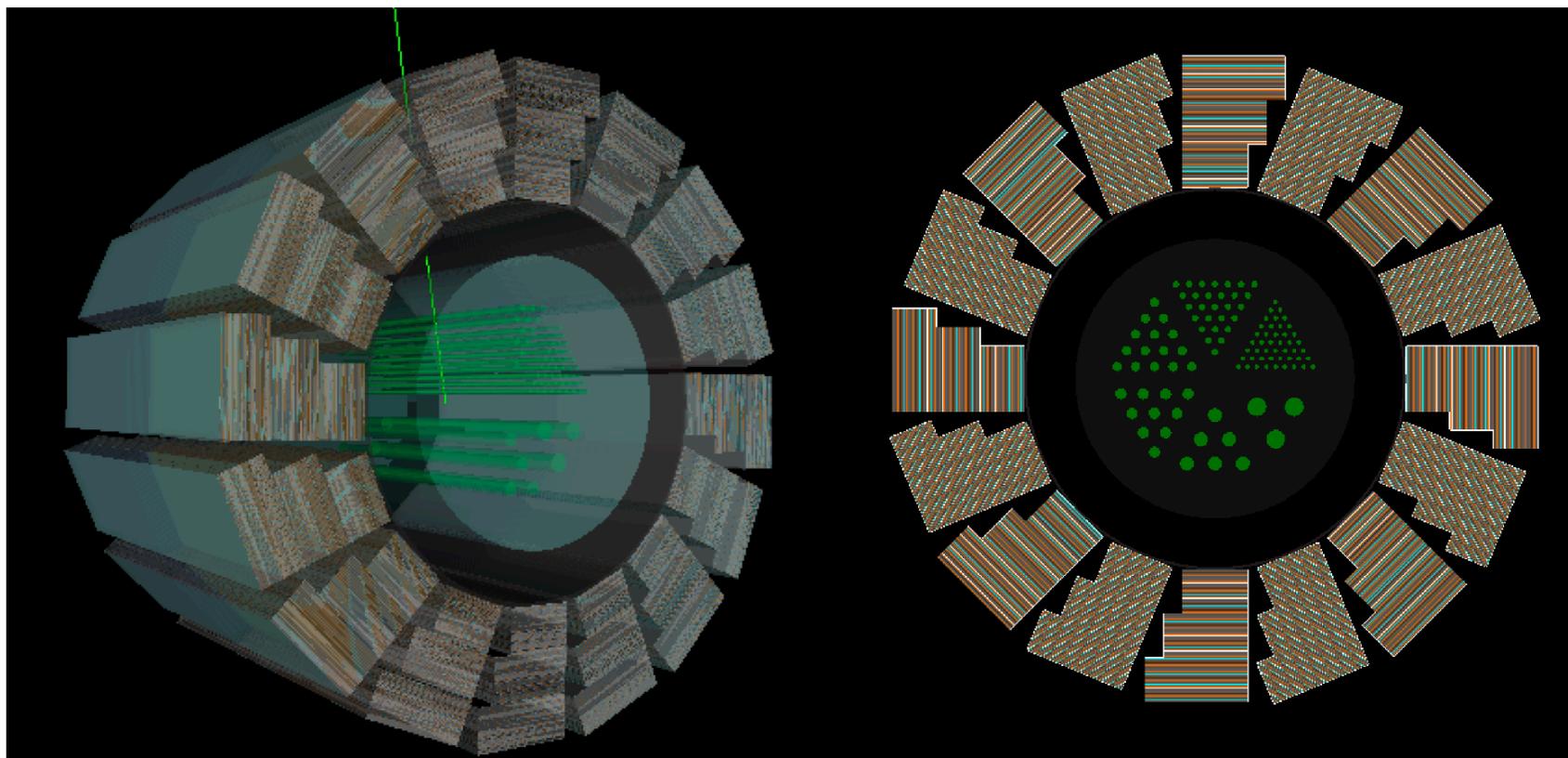
Pixel	Time resolution [ps]	
	w/o position correction	with position correction
Downstream Small	$202.3 \pm 0.8$	$167.7 \pm 0.7$
Upstream Small	$219.0 \pm 0.7$	$188.2 \pm 0.6$
Upstream Large	$265 \pm 1$	$212 \pm 1$

Despite lack of vital processing steps ToF no so far away from 100ps for MIP's expected

- TT-PET Collaboration
- Scanner Overview
- Monolithic Chip
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- TOF simulation
- Prototype-0

# Simple phantom simulation

- Geant4 simulation
- Scanner geometry with acrylic phantom (variable rod sizes) filled with F18 (50MBq)



Phantom  $D = 15\text{mm}$

Rod  $d = 0.5\text{mm}$

0.7mm

1.0mm

1.2mm

1.5mm

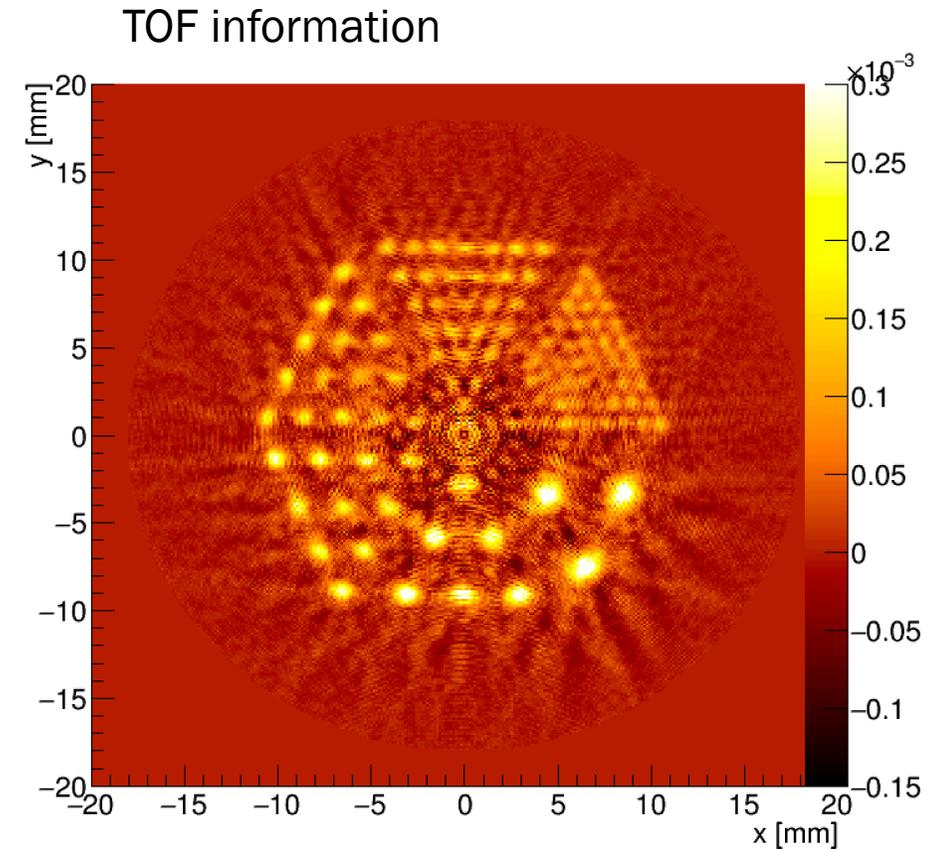
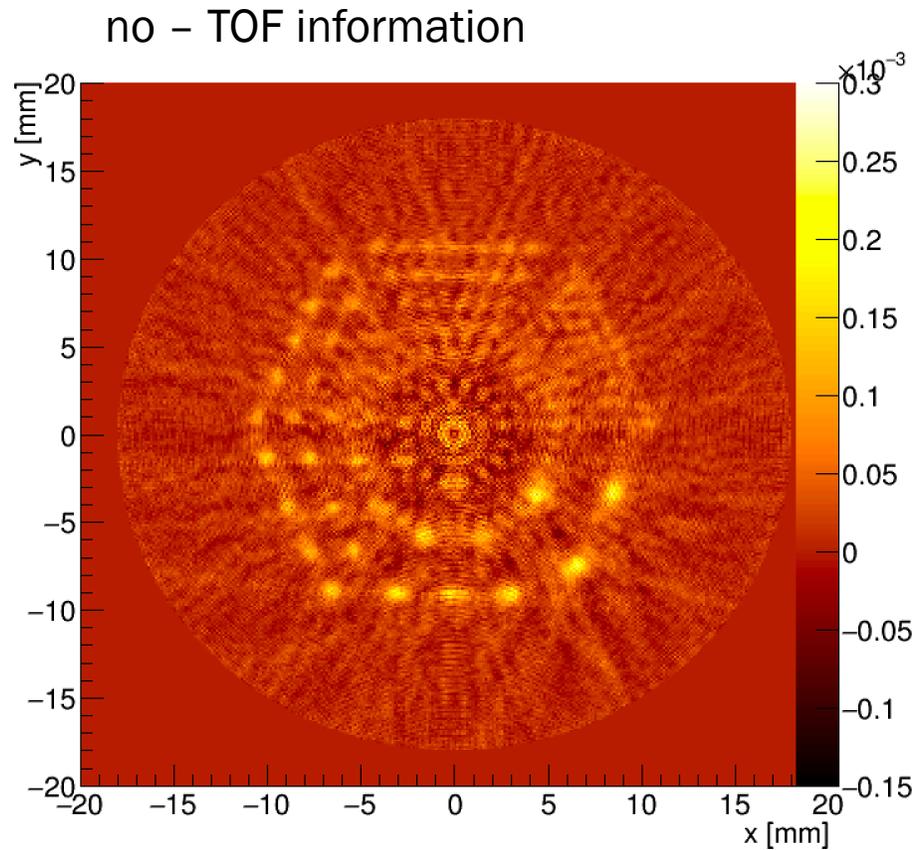
2.0mm

Inter-rod distance

$2d$

# Simple phantom simulation

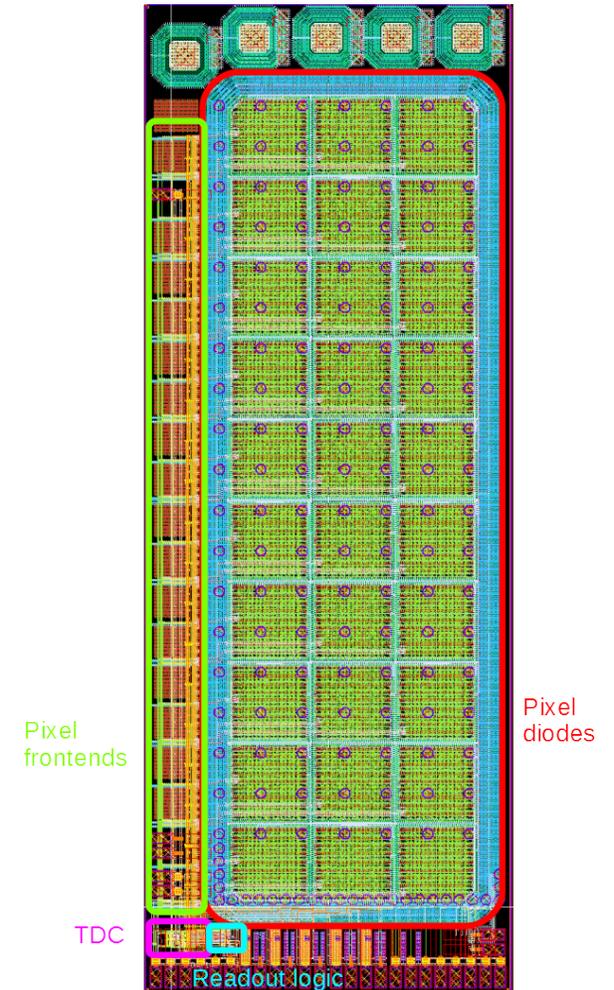
- Simple reconstruction (FBP)
- $>10^9$  events simulated
- Expected detector response included



- TT-PET Collaboration
- Scanner Overview
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- TOF simulation
- **Prototype-0**

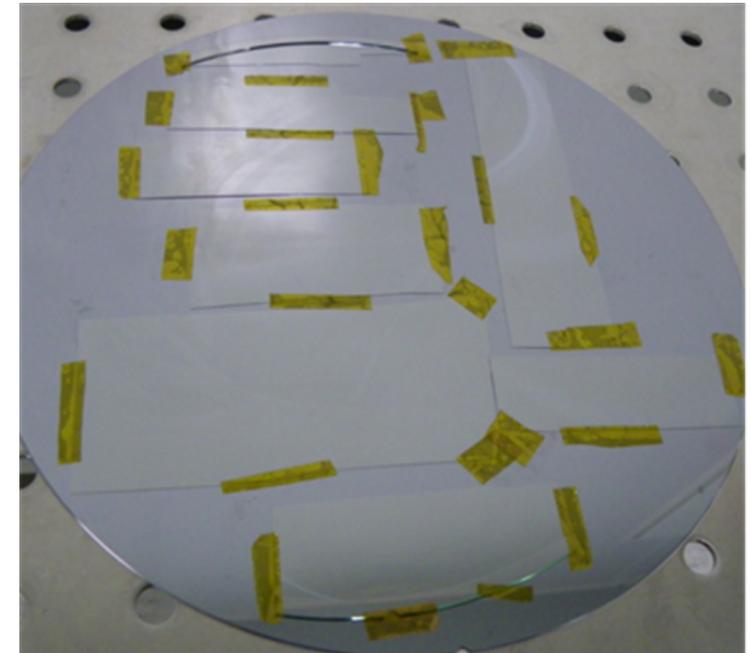
# Prototype-0

- A fully featured prototype was submitted in April 2017 (MPW run)
- It has a smaller matrix (30 pixels) and a simplified readout scheme, but it's otherwise complete
- Low resistivity wafer first (check HV doesn't interfere with LV electronics)
- It's useful to test integration issues (power delivery, crosstalk...)

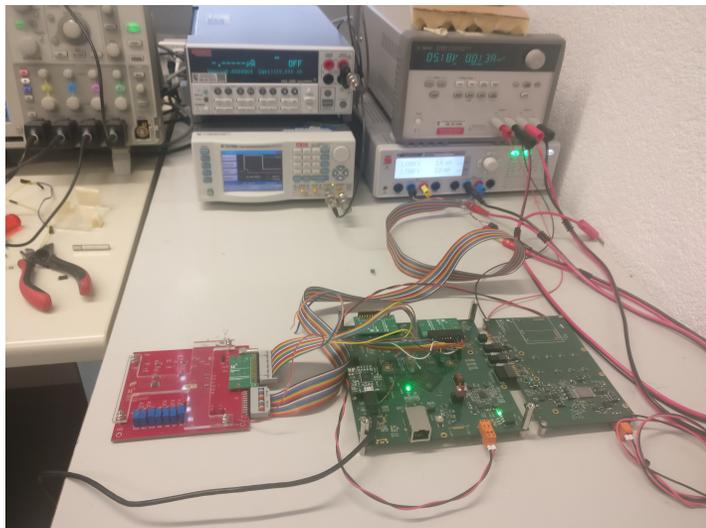


# Prototype-0 HR

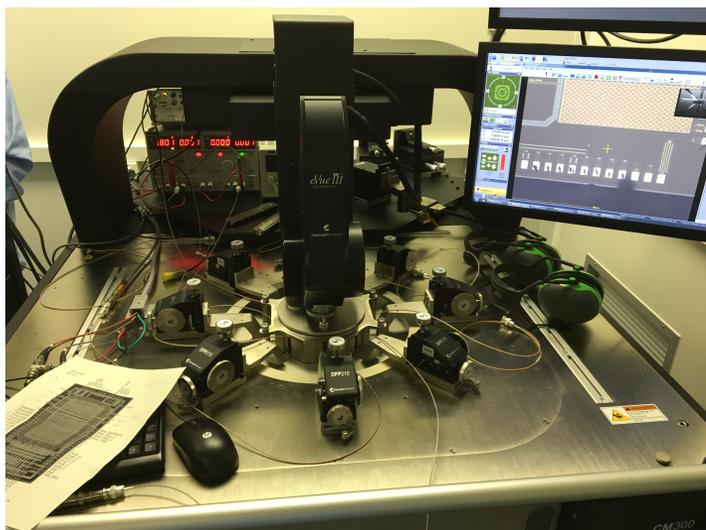
- Delays in high resistivity delivery
- Thin wafers broke at backside metalisation and dicing stage
- 4 MPW runs per year, ~4 month process time
- HR backside metalised diced chips delivered last week
- HV tested to work upto target 300V



# Test setups



- DAQ software and firmware has already been developed
- Continued to to be improved
- Additional power module for the each Tower control FPGA board has been completed
- Top left: Prototype-0 (red PCB) being tested at Bern



- Probe station used to characterize monolithic chips before being mounted on PCB's for testing (R&D)

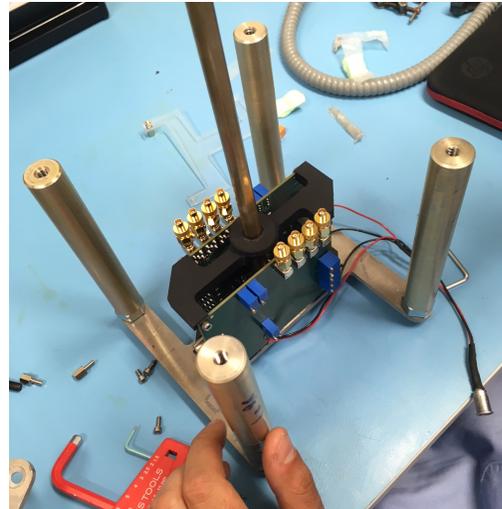
# Future Tests



- Now that Prototype-0 HR has been delivered
- ToF / coincidence measurements will be performed in the coming weeks at Bern cyclotron using custom F18 phantom's
- ToF measurements using cyclotron 18 MeV proton beam
- CFRP support + protective skin going through final revisions



dforshaw@cern.ch



PSMR2018

- Na22 ToF at Geneva University shortly
- Final monolithic design submission expected Sept/October 2018



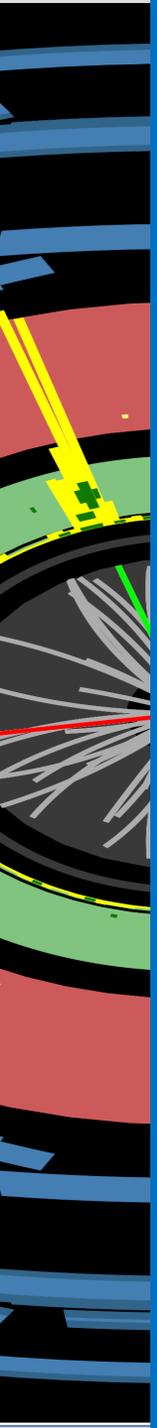
# Thank You

# Questions?

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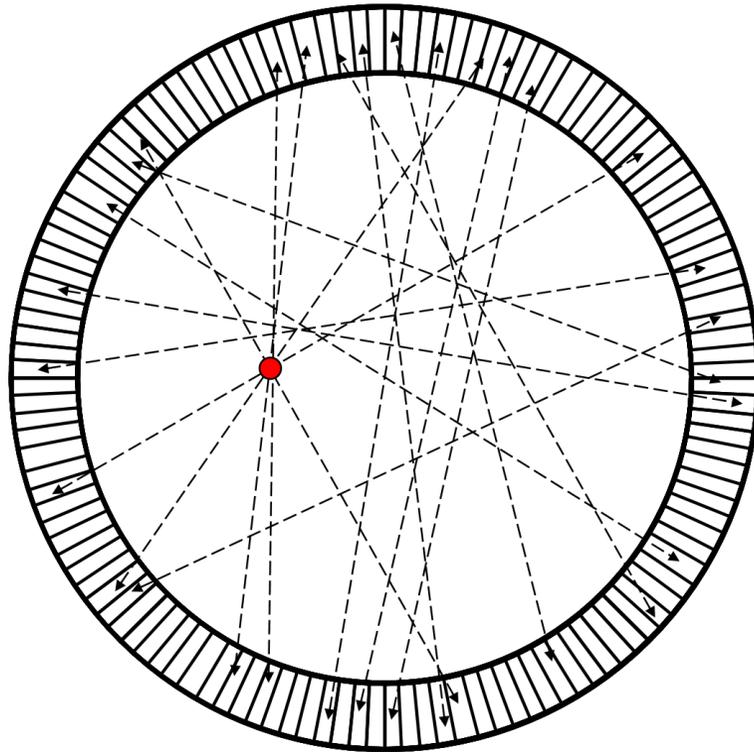
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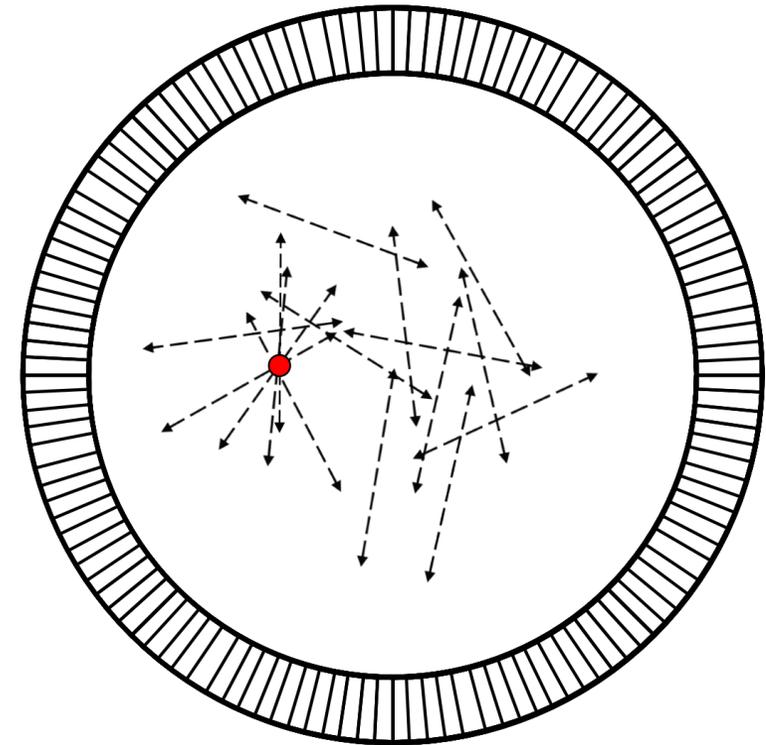
# Backup

# Why use Time-of-Flight?

Conventional PET



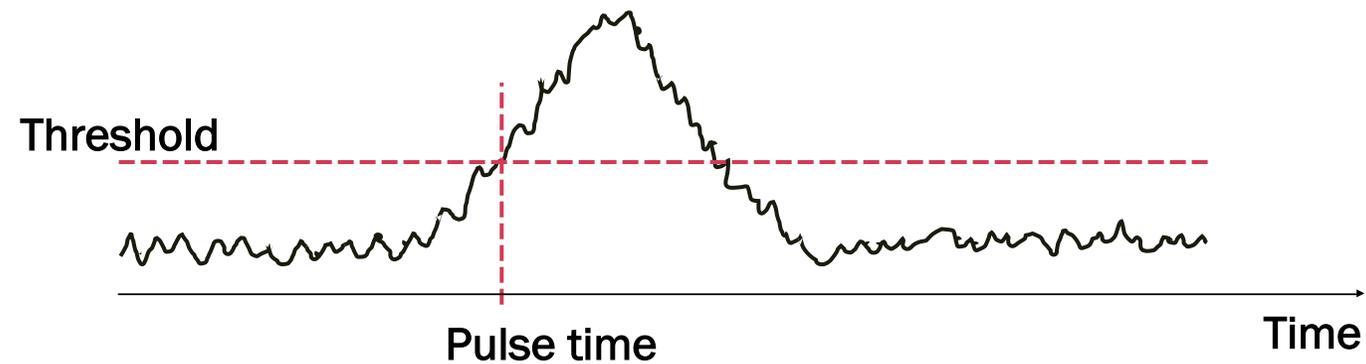
TOF PET



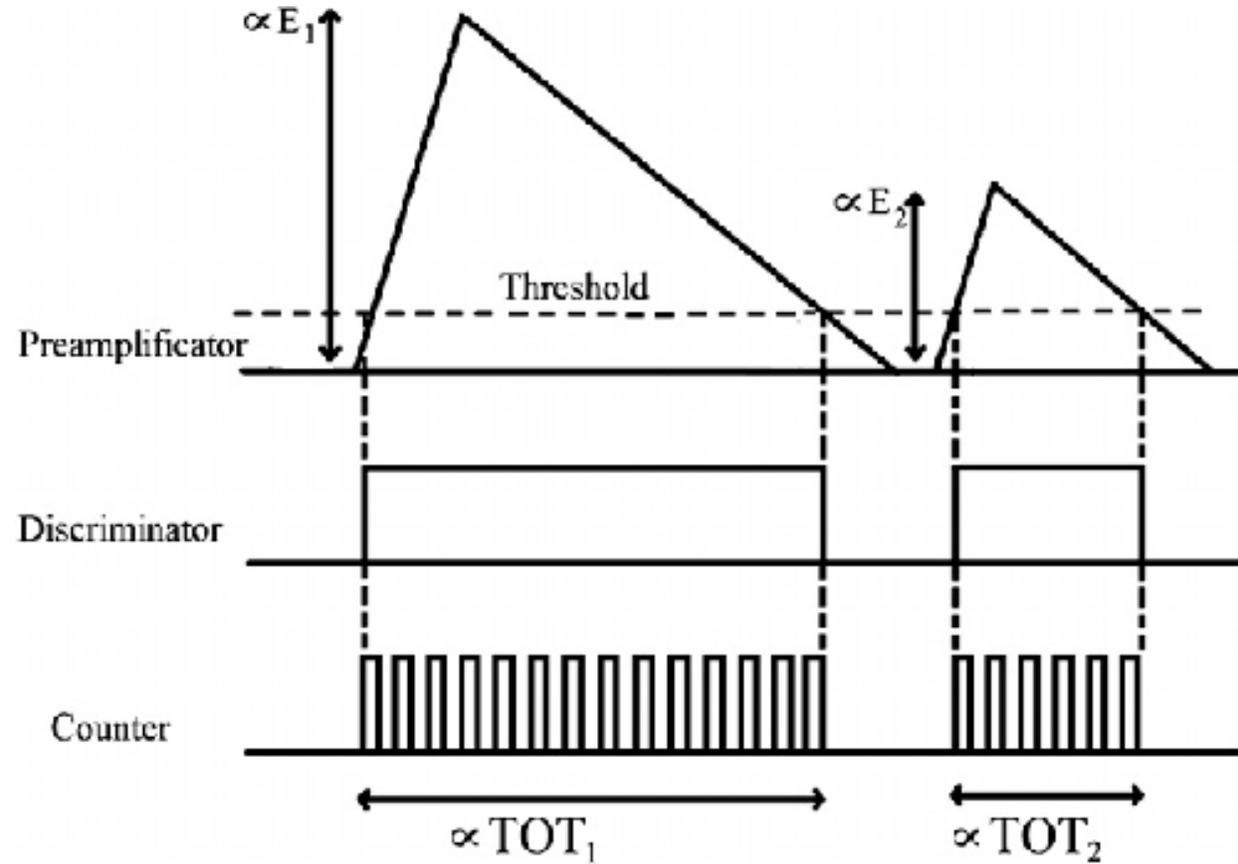
# Time resolution

- Detector time resolution depends mostly on the amplifier performance.

$$\sigma_t = \frac{\sigma_V}{\frac{dV}{dt}} \cong \frac{t_{rise}}{\text{Signal}/\text{Noise}}$$

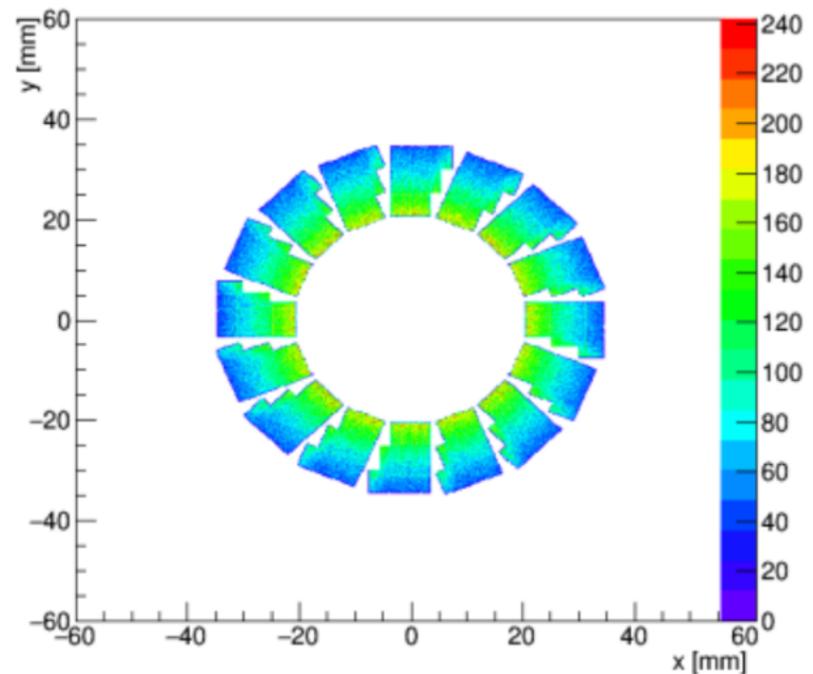
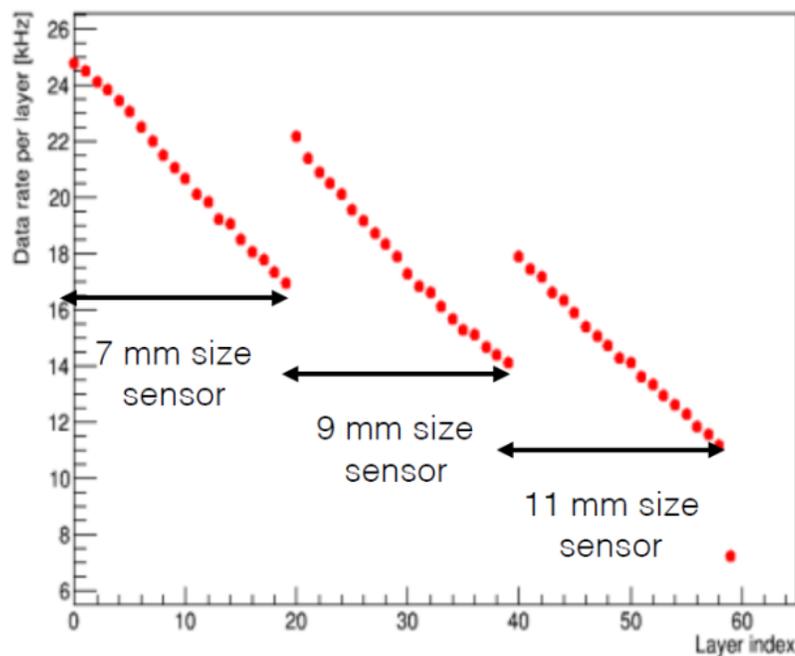


# Time-over-Threshold



# Event Rate and Data Pressure

- Hit rate for a 50 MBq point source is still < 25kHz per layer



- Geant4 Simulation

# Monolithic Test chip

